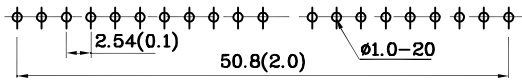


## Features

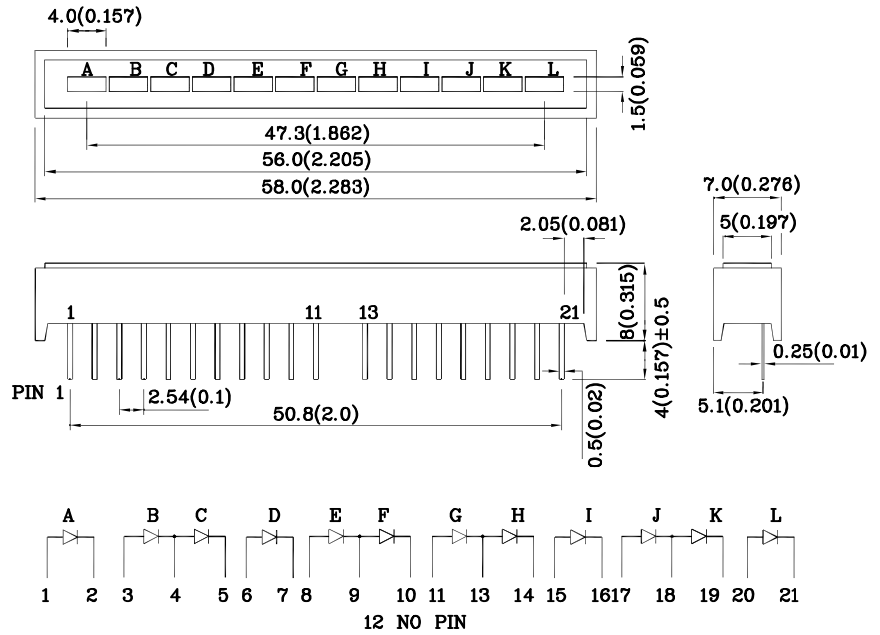
- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- Configuration: Black face w/ white segments
- RoHS compliant



### RECOMMENDED PCB LAYOUT



## Package Schematics



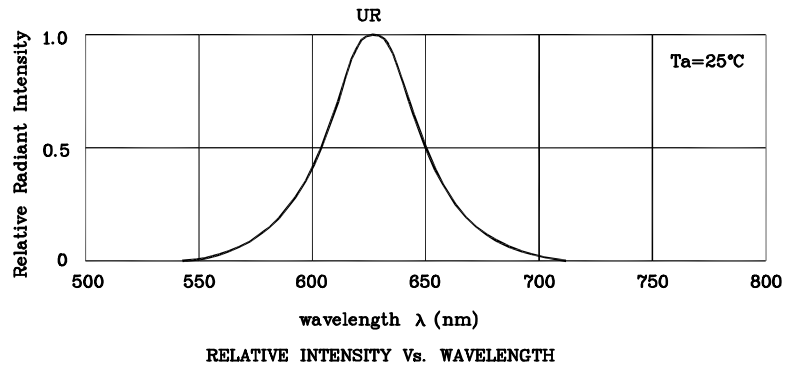
### Notes:

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

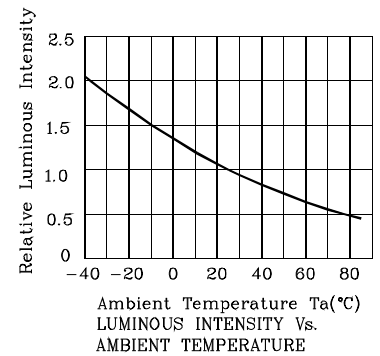
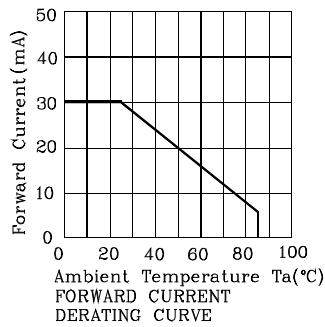
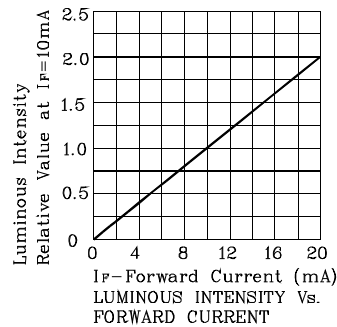
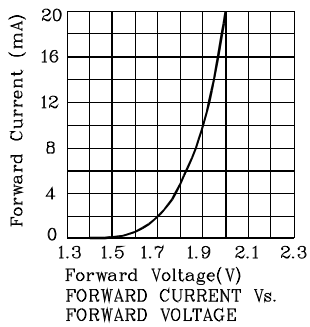
| Absolute Maximum Ratings<br>(T <sub>A</sub> =25°C)             |                       | UR<br>(GaAsP/GaP) | Unit |
|----------------------------------------------------------------|-----------------------|-------------------|------|
| Reverse Voltage                                                | V <sub>R</sub>        | 5                 | V    |
| Forward Current                                                | I <sub>F</sub>        | 30                | mA   |
| Forward Current (Peak)<br>1/10 Duty Cycle<br>0.1ms Pulse Width | i <sub>FS</sub>       | 160               | mA   |
| Power Dissipation                                              | P <sub>D</sub>        | 75                | mW   |
| Operating Temperature                                          | T <sub>A</sub>        | -40 ~ +85         | °C   |
| Storage Temperature                                            | T <sub>stg</sub>      | -40 ~ +85         |      |
| Lead Solder Temperature<br>[2mm Below Package Base]            | 260°C For 3-5 Seconds |                   |      |

| Operating Characteristics<br>( $T_A=25^\circ\text{C}$ )                     |                 | UR<br>(GaAsP/GaP) | Unit          |
|-----------------------------------------------------------------------------|-----------------|-------------------|---------------|
| Forward Voltage (Typ.)<br>( $I_F=10\text{mA}$ )                             | $V_F$           | 1.9               | V             |
| Forward Voltage (Max.)<br>( $I_F=10\text{mA}$ )                             | $V_F$           | 2.5               | V             |
| Reverse Current (Max.)<br>( $V_R=5\text{V}$ )                               | $I_R$           | 10                | $\mu\text{A}$ |
| Wavelength of Peak<br>Emission (Typ.)<br>( $I_F=10\text{mA}$ )              | $\lambda_P$     | 627               | nm            |
| Wavelength of Dominant<br>Emission (Typ.)<br>( $I_F=10\text{mA}$ )          | $\lambda_D$     | 625               | nm            |
| Spectral Line Full Width<br>At Half-Maximum (Typ.)<br>( $I_F=10\text{mA}$ ) | $\Delta\lambda$ | 45                | nm            |
| Capacitance (Typ.)<br>( $V_F=0\text{V}$ , $f=1\text{MHz}$ )                 | $C$             | 15                | pF            |

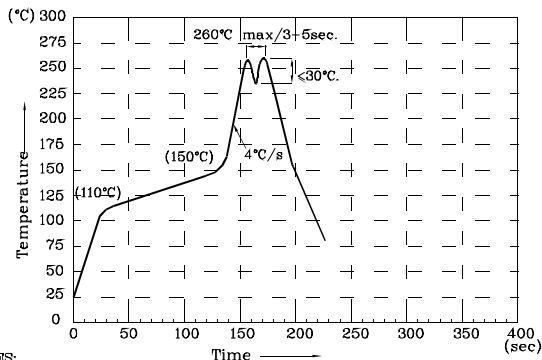
| Part<br>Number | Emitting<br>Color | Emitting<br>Material | Luminous<br>Intensity<br>(I <sub>F</sub> =10mA)<br>ucd |      | Wavelength<br>nm<br>λP | Description                      |
|----------------|-------------------|----------------------|--------------------------------------------------------|------|------------------------|----------------------------------|
|                |                   |                      | min.                                                   | typ. |                        |                                  |
| XHURX12DWB     | Red               | GaAsP/GaP            | 3600                                                   | 9590 | 627                    | 12 Segments<br>Bar graph-Display |



# ❖ UR



## Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



### NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

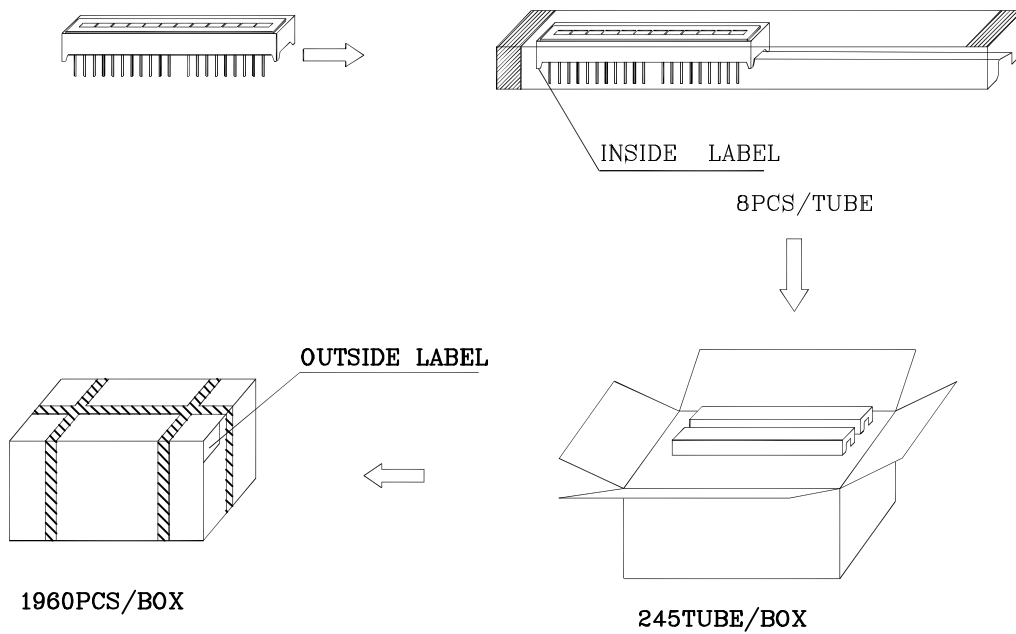
### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

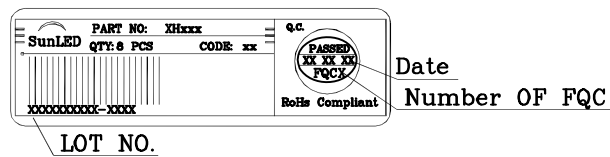
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

## PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

